12-28-00

PATENT APPLICATION TRANSMITTAL LETTER

(Large Entity)

Docket No. **E0520CIP**

TO THE ASSISTANT COMMISSIONER FOR PATENTS

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Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F. C. Marxsen, Steven A. Avanzino

For: "PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY US SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER CORROSION INHIBITING PROPERTIES"

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⊠ 12 (twelve)

sheets of drawings.

☐ A certified copy of a

☑ Declaration

Signed.

application. ☐ Unsigned.

Power of Attorney

☐ Information Disclosure Statement

□ Preliminary Amendment

☑ Other: Recordation Cover Sheet and Assignment; Request and Certification under 35 USC 122(b)(2)(B)(i)

CLAIMS AS FILED

For	#Filed	#Allowed	#Extra		Rate	Fee
Total Claims	73	- 20 =	53	×	\$18.00	\$954.00
ndep. Claims	5	- 3 =	2	×	\$80.00	\$160.00
Multiple Dependen	ıt Claims (checl	(if applicable)				\$0.00
					BASIC FEE	\$710.00
	·		, <u>, , , , , , , , , , , , , , , , , , </u>		TOTAL FILING FEE	\$1,824.00

A check in the amount of

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▼ The Commissioner is hereby authorized to charge and credit Deposit Account No.

\$1,824.00

01-0365

as described below. A duplicate copy of this sheet is enclosed. as filing fee.

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Credit any overpayment.

☑ Charge any additional filing fees required under 37 C.F.R. 1.16 and 1.17.

☐ Charge the issue fee set in 37 C.F.F. 1.18 at the mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).

December 26, 2000

He boan W. Werour

Deborah W. Wenocur, Reg. No 40,221

Agent for Applicant

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P.O. Box 3453

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CC:

Dated:

Beboran W. Werrous

Dated: December 26, 2000

Deborah W. Wenocur, Reg. No. 40,221 Agent for Applicant Advanced Micro Devices, Inc. Technology Law Dept. M/S 68 One AMD Place

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Sunnyvale, CA 94088-3453

I certify that this document and fee is being deposited on Dec. 26, 2000 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C.

Bevoran W. Wenow

Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC:

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REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)

First Named Inventor		Kashmir S. Sahota	
Title	Prevention of Interconnects	of Precipitation Defects on Copper ets During CMP By Use of Solutions	
Atty Do	ocket Number	E0520CIP	

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

December 25, 2000

Date

Albranto, Wenoen

Signature

Deborah W. Wenocur

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant must notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).

CERTIFICATE OF	Docket No.							
Applicant(s): Kashmir S	E0520CIP							
Serial No.	Group Art Unit							
	Filing Date							
Invention: Prevention of Precipitation Defects on Copper Interconnects During CMP By Use of Solutions Containing Organic Compounds With Silica Adsorption and Copper Corrosion Inhibiting Properties								
I hereby certify that the	e following correspondence:		Je843 U.S. 09/74919					
	(Ic'entify type	of correspondence)						
is being deposited wit	n the United States Postal Servi	ce "Express Mail Post Office	to Addressee" service under					
37 CFR 1.10 in an env	velope addressed to: The Assista	ant Commissioner for Patents,	Washington, D.C. 20231 on					
December (Date								
<u> </u>		Deborah W.						
		(Typed or Printed Name of Person ALLYOULUM W. (Mailing Correspondence)					
(Signature of Person Mailing Correspondence)								
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